

# MMBV432LT1

Preferred Device

## Silicon Tuning Diode

This device is designed for FM tuning, general frequency control and tuning, or any top-of-the-line application requiring back-to-back diode configuration for minimum signal distortion and detuning. This device is supplied in the SOT-23 plastic package for high volume, pick and place assembly requirements.

### Features

- High Figure of Merit –  $Q = 150$  (Typ) @  $V_R = 2.0$  Vdc,  $f = 100$  MHz
- Guaranteed Capacitance Range
- Dual Diodes – Save Space and Reduce Cost
- Surface Mount Package
- Available in 8 mm Tape and Reel
- Monolithic Chip Provides Improved Matching – Guaranteed  $\pm 1.0\%$  (Max) Over Specified Tuning Range
- Pb-Free Package is Available

### MAXIMUM RATINGS (Each Diode)

Rating	Symbol	Value	Unit
Reverse Voltage	$V_R$	14	Vdc
Forward Current	$I_F$	200	mAdc
Total Power Dissipation @ $T_A = 25^\circ\text{C}$ Derate above $25^\circ\text{C}$	$P_D$	225 1.8	mW mW/ $^\circ\text{C}$
Junction Temperature	$T_J$	+125	$^\circ\text{C}$
Storage Temperature Range	$T_{stg}$	-55 to +125	$^\circ\text{C}$

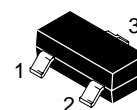
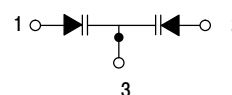
Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.



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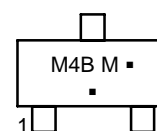
<http://onsemi.com>

## DUAL VOLTAGE VARIABLE CAPACITANCE DIODE



SOT-23 (TO-236)  
CASE 318  
STYLE 9

### MARKING DIAGRAM



M4B = Specific Device Code  
M = Date Code\*  
▪ = Pb-Free Package

(Note: Microdot may be in either location)

\*Date Code orientation and/or overbar may vary depending upon manufacturing location.

### ORDERING INFORMATION

Device	Package	Shipping†
MMBV432LT1	SOT-23	3,000 / Tape & Reel
MMBV432LT1G	SOT-23 (Pb-Free)	3,000 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

Preferred devices are recommended choices for future use and best overall value.

# MMBV432LT1

## ELECTRICAL CHARACTERISTICS (EACH DIODE) ( $T_A = 25^\circ\text{C}$ unless otherwise noted)

Characteristic	Symbol	Min	Typ	Max	Unit
Reverse Breakdown Voltage ( $I_R = 10 \mu\text{A}$ )	$V_{(BR)R}$	14	–	–	Vdc
Reverse Voltage Leakage Current ( $V_R = 9.0 \text{ Vdc}$ )	$I_R$	–	–	100	nAdc
Diode Capacitance ( $V_R = 2.0 \text{ Vdc}$ , $f = 1.0 \text{ MHz}$ )	$C_T$	43	–	48.1	pF
Capacitance Ratio $C_2/C_8$ ( $f = 1.0 \text{ MHz}$ )	$C_R$	1.5	–	2.0	–
Figure of Merit ( $V_R = 2.0 \text{ Vdc}$ , $f = 100 \text{ MHz}$ )	Q	100	150	–	–

# MMBV432LT1

## TYPICAL CHARACTERISTICS (Each Diode)

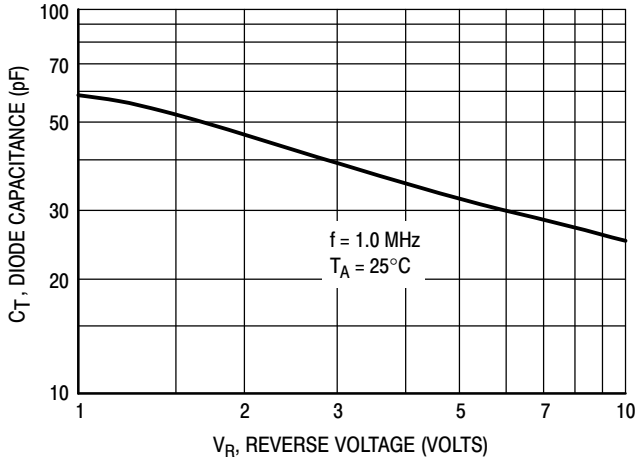


Figure 1. Diode Capacitance

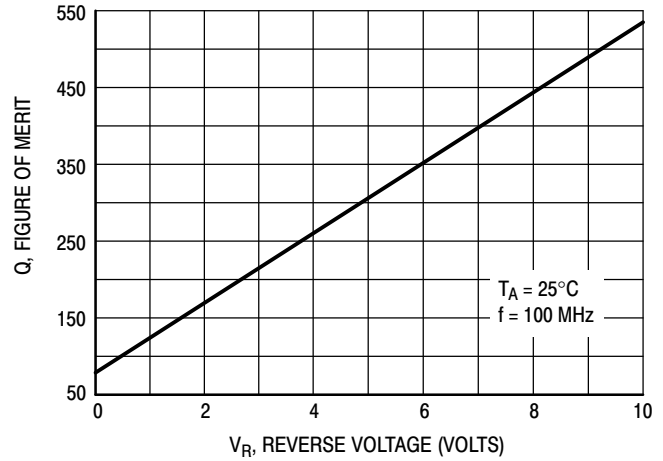


Figure 2. Figure of Merit versus Voltage

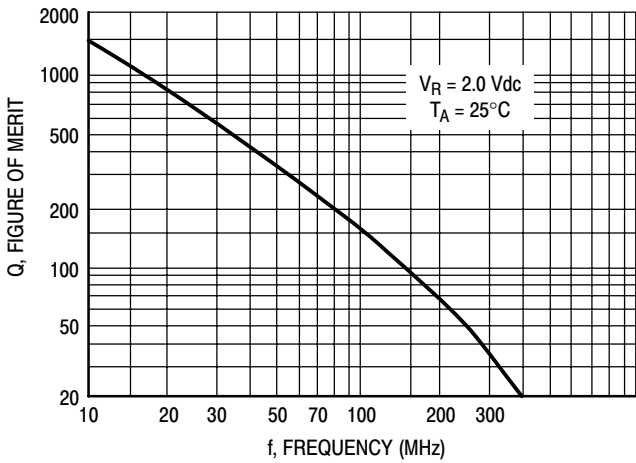


Figure 3. Figure of Merit versus Frequency

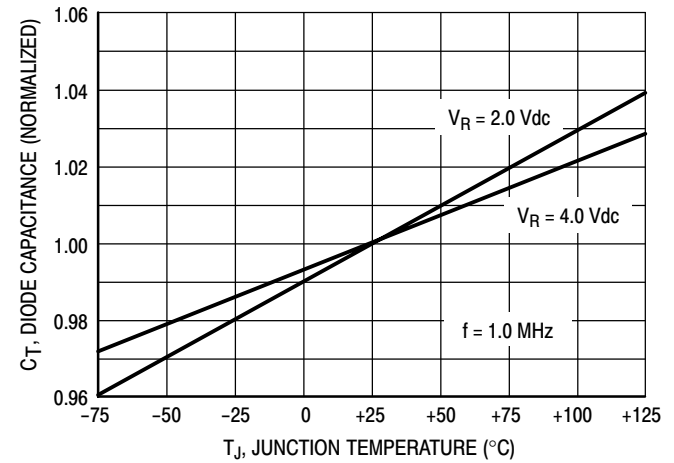


Figure 4. Diode Capacitance versus Temperature

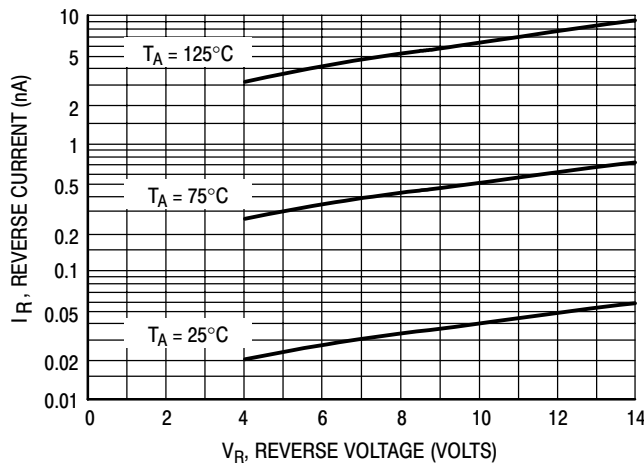
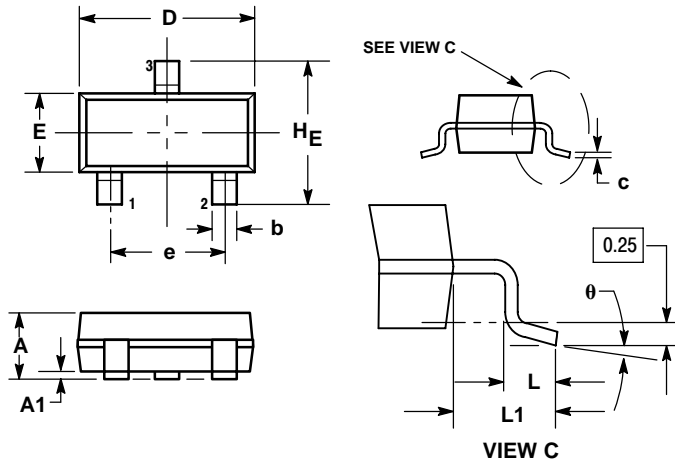


Figure 5. Reverse Current versus Reverse Voltage

# MMBV432LT1

## PACKAGE DIMENSIONS

SOT-23 (TO-236)  
CASE 318-08  
ISSUE AN



NOTES:

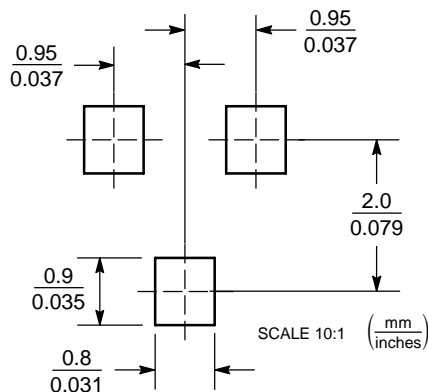
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.
4. 318-01 THRU -07 AND -09 OBSOLETE, NEW STANDARD 318-08.

DIM	MILLIMETERS			INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	0.89	1.00	1.11	0.035	0.040	0.044
A1	0.01	0.06	0.10	0.001	0.002	0.004
b	0.37	0.44	0.50	0.015	0.018	0.020
c	0.09	0.13	0.18	0.003	0.005	0.007
D	2.80	2.90	3.04	0.110	0.114	0.120
E	1.20	1.30	1.40	0.047	0.051	0.055
e	1.78	1.90	2.04	0.070	0.075	0.081
L	0.10	0.20	0.30	0.004	0.008	0.012
L1	0.35	0.54	0.69	0.014	0.021	0.029
HE	2.10	2.40	2.64	0.083	0.094	0.104

STYLE 9:

1. ANODE
2. ANODE
3. CATHODE

### SOLDERING FOOTPRINT\*



\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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